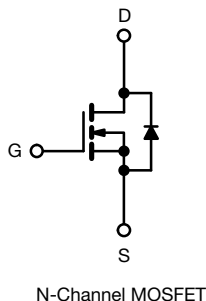
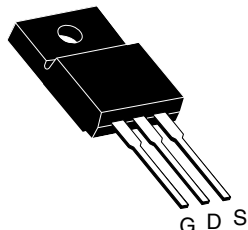


E Series Power MOSFET

TO-220 FULLPAK


FEATURES

- Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

PRODUCT SUMMARY

| | | |
|---|-----------------|-----|
| V_{DS} (V) at T_J max. | 700 | |
| $R_{DS(on)}$ max. (Ω) at 25 °C | $V_{GS} = 10$ V | 0.6 |
| Q_g max. (nC) | 48 | |
| Q_{gs} (nC) | 6 | |
| Q_{gd} (nC) | 11 | |
| Configuration | Single | |

ORDERING INFORMATION

| | |
|---------------------------------|----------------|
| Package | TO-220 FULLPAK |
| Lead (Pb)-free and Halogen-free | SiHF6N65E-GE3 |

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|---|----------------|----------------|------|
| Drain-Source Voltage | V_{DS} | 650 | V |
| Gate-Source Voltage | V_{GS} | ± 30 | |
| Continuous Drain Current ($T_J = 150$ °C) ^e | I_D | $T_C = 25$ °C | A |
| | | $T_C = 100$ °C | |
| Pulsed Drain Current ^a | I_{DM} | 18 | |
| Linear Derating Factor | | 0.63 | W/°C |
| Single Pulse Avalanche Energy ^b | E_{AS} | 56 | mJ |
| Maximum Power Dissipation | P_D | 31 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 to +150 | °C |
| Drain-Source Voltage Slope | dV/dt | $T_J = 125$ °C | V/ns |
| Reverse Diode dV/dt ^d | | | |
| Soldering Recommendations (Peak temperature) ^c | For 10 s | 300 | °C |
| Mounting Torque | M3 screw | 0.6 | Nm |


Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 2$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.
- Limited by maximum junction temperature.

**THERMAL RESISTANCE RATINGS**

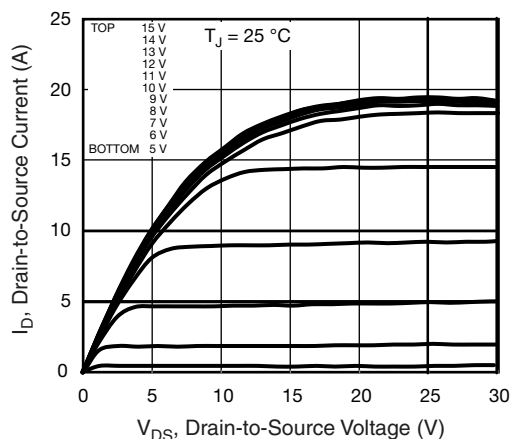
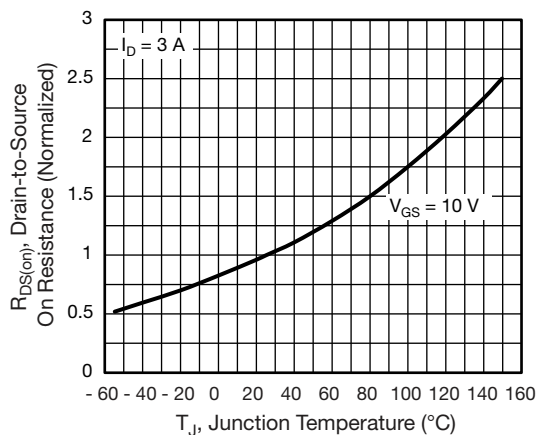
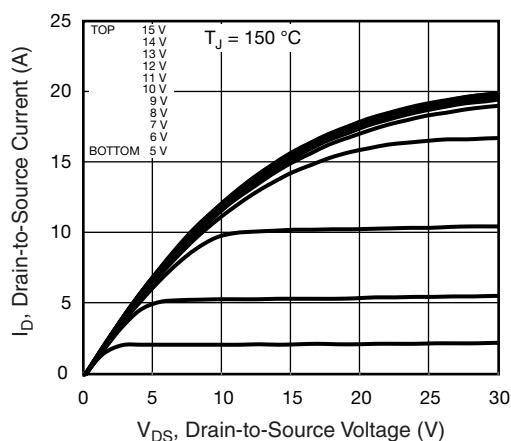
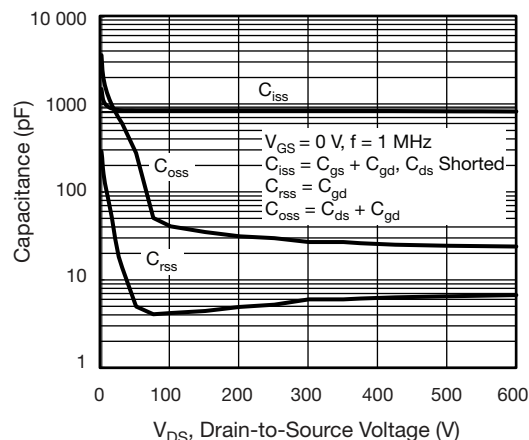
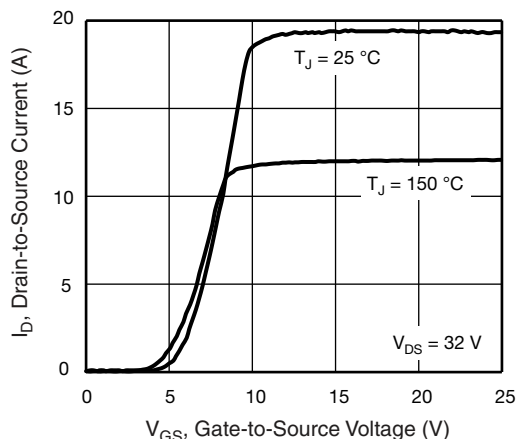
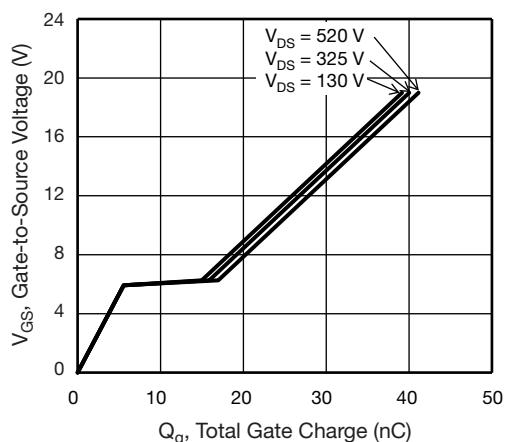
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum Junction-to-Ambient | R_{thJA} | - | 65 | °C/W |
| Maximum Junction-to-Case (Drain) | R_{thJC} | - | 4.0 | |

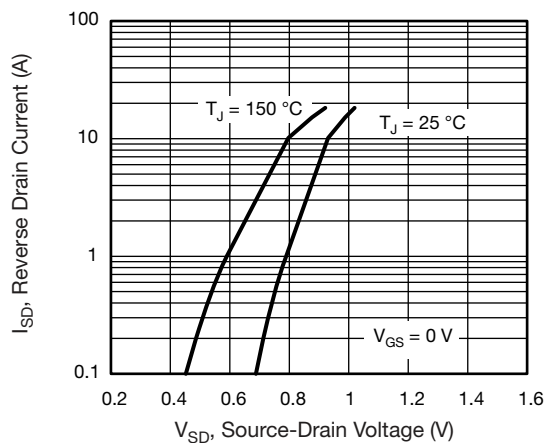
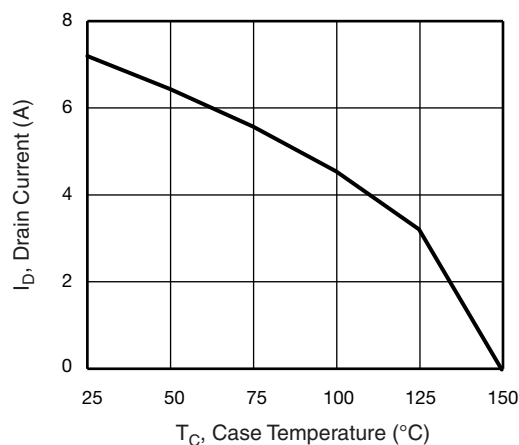
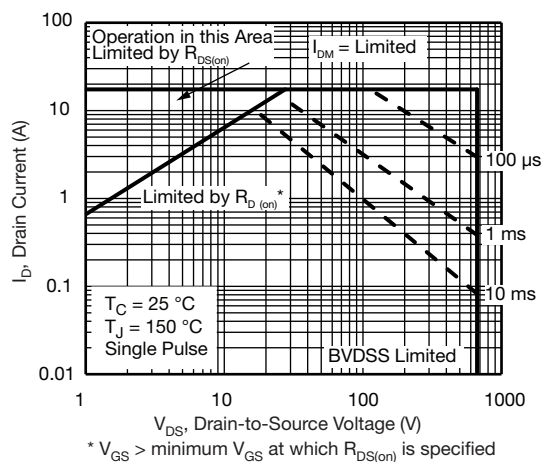
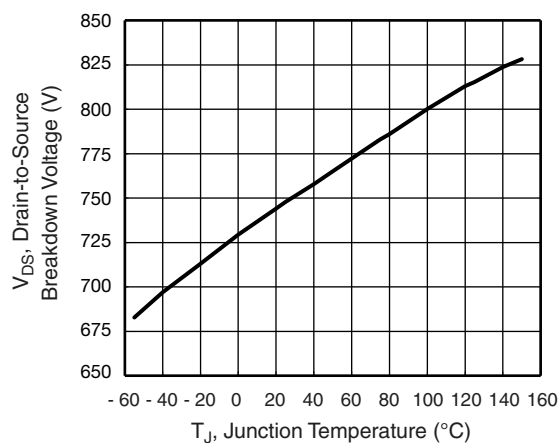
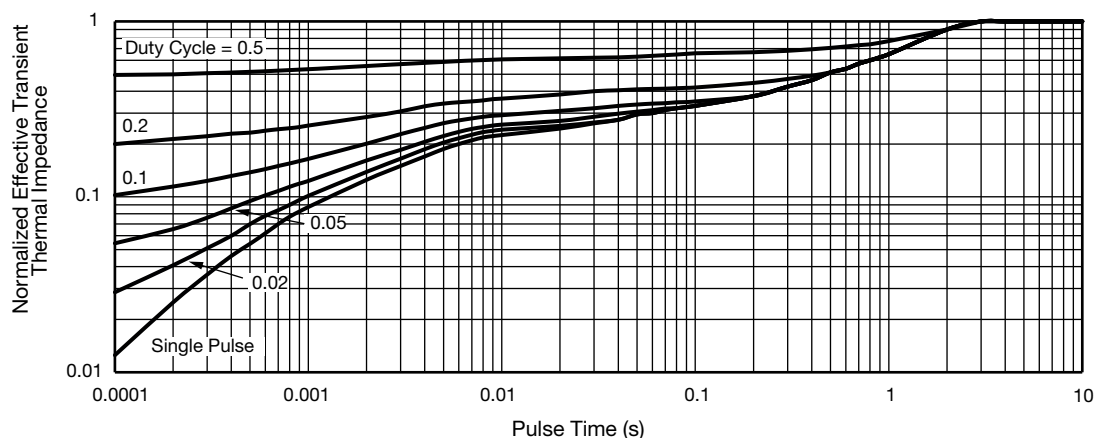
SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

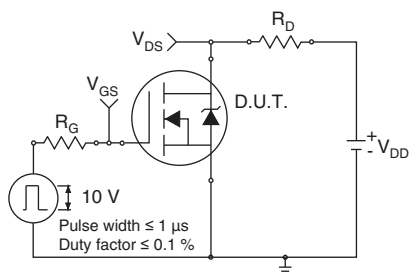
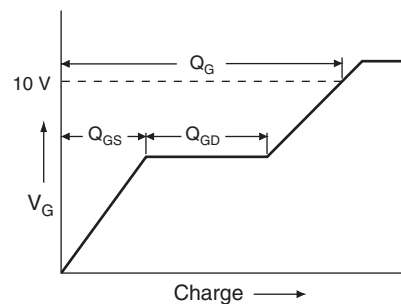
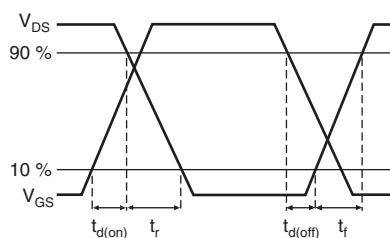
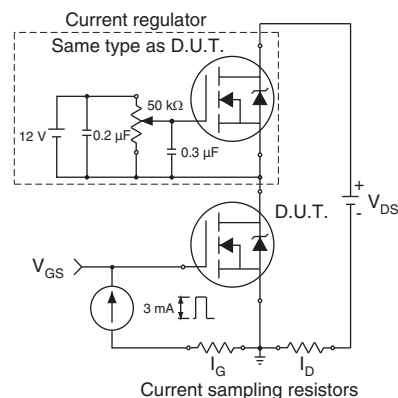
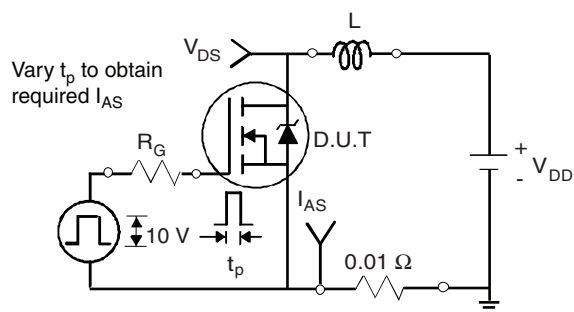
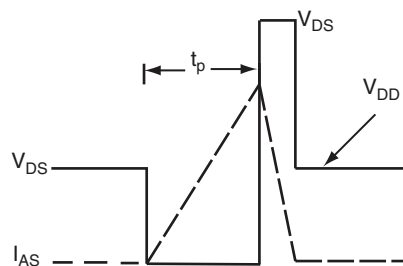
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|----------------------------------|---|---|------|------|-------|------|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | | 650 | - | - | V |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | Reference to 25 °C, I _D = 1 mA | | - | 0.73 | - | V/°C |
| Gate-Source Threshold Voltage (N) | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | | 2 | - | 4 | V |
| Gate-Source Leakage | I _{GSS} | V _{GS} = ± 20 V | | - | - | ± 100 | nA |
| | | V _{GS} = ± 30 V | | - | - | ± 1 | μA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 650 V, V _{GS} = 0 V | | - | - | 1 | μA |
| | | V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125 °C | | - | - | 10 | |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 3 A | - | 0.5 | 0.6 | Ω |
| Forward Transconductance | g _{fs} | V _{DS} = 30 V, I _D = 3 A | | - | 2 | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz | | - | 820 | - | pF |
| Output Capacitance | C _{oss} | | | - | 40 | - | |
| Reverse Transfer Capacitance | C _{rss} | | | - | 4 | - | |
| Effective Output Capacitance, Energy Related ^a | C _{o(er)} | V _{DS} = 0 V to 520 V, V _{GS} = 0 V | | - | 36 | - | |
| Effective Output Capacitance, Time Related ^b | C _{o(tr)} | | | - | 117 | - | |
| Total Gate Charge | Q _g | V _{GS} = 10 V | I _D = 3 A, V _{DS} = 520 V | - | 24 | 48 | nC |
| Gate-Source Charge | Q _{gs} | | | - | 6 | - | |
| Gate-Drain Charge | Q _{gd} | | | - | 11 | - | |
| Turn-On Delay Time | t _{d(on)} | V _{DD} = 520 V, I _D = 3 A, V _{GS} = 10 V, R _g = 9.1 Ω | | - | 14 | 28 | ns |
| Rise Time | t _r | | | - | 12 | 24 | |
| Turn-Off Delay Time | t _{d(off)} | | | - | 30 | 60 | |
| Fall Time | t _f | | | - | 20 | 40 | |
| Gate Input Resistance | R _g | f = 1 MHz, open drain | | - | 1.4 | - | Ω |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I _S | MOSFET symbol showing the integral reverse p - n junction diode  | | - | - | 7 | A |
| Pulsed Diode Forward Current | I _{SM} | | | - | - | 18 | |
| Diode Forward Voltage | V _{SD} | T _J = 25 °C, I _S = 3 A, V _{GS} = 0 V | | - | - | 1.3 | V |
| Reverse Recovery Time | t _{rr} | T _J = 25 °C, I _F = I _S = 3 A, dI/dt = 100 A/μs, V _R = 25 V | | - | 237 | - | ns |
| Reverse Recovery Charge | Q _{rr} | | | - | 2.2 | - | μC |
| Reverse Recovery Current | I _{RRM} | | | - | 16 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage


Fig. 7 - Typical Source-Drain Diode Forward Voltage

Fig. 9 - Maximum Drain Current vs. Case Temperature

Fig. 8 - Maximum Safe Operating Area

Fig. 10 - Temperature vs. Drain-to-Source Voltage

Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case


Fig. 12 - Switching Time Test Circuit

Fig. 16 - Basic Gate Charge Waveform

Fig. 13 - Switching Time Waveforms

Fig. 17 - Gate Charge Test Circuit

Fig. 14 - Unclamped Inductive Test Circuit

Fig. 15 - Unclamped Inductive Waveforms


Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 18 - For N-Channel

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TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9



| DIM. | MILLIMETERS | | |
|------|-------------|-------|-------|
| | MIN. | NOM. | MAX. |
| A | 4.60 | 4.70 | 4.80 |
| b | 0.70 | 0.80 | 0.91 |
| b1 | 1.20 | 1.30 | 1.47 |
| b2 | 1.10 | 1.20 | 1.30 |
| C | 0.45 | 0.50 | 0.63 |
| D | 15.80 | 15.87 | 15.97 |
| e | 2.54 BSC | | |
| E | 10.00 | 10.10 | 10.30 |
| F | 2.44 | 2.54 | 2.64 |
| G | 6.50 | 6.70 | 6.90 |
| L | 12.90 | 13.10 | 13.30 |
| L1 | 3.13 | 3.23 | 3.33 |
| Q | 2.65 | 2.75 | 2.85 |
| Q1 | 3.20 | 3.30 | 3.40 |
| Ø R | 3.08 | 3.18 | 3.28 |

Notes

1. To be used only for process drawing
2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
3. All critical dimensions should C meet $C_{pk} > 1.33$
4. All dimensions include burrs and plating thickness
5. No chipping or package damage
6. Facility code will be the 1st character located at the 2nd row of the unit marking

**OPTION 2: FACILITY CODE = Y**

| DIM. | MILLIMETERS | | INCHES | |
|------|-------------|--------|-----------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.570 | 4.830 | 0.180 | 0.190 |
| A1 | 2.570 | 2.830 | 0.101 | 0.111 |
| A2 | 2.510 | 2.850 | 0.099 | 0.112 |
| b | 0.622 | 0.890 | 0.024 | 0.035 |
| b2 | 1.229 | 1.400 | 0.048 | 0.055 |
| b3 | 1.229 | 1.400 | 0.048 | 0.055 |
| c | 0.440 | 0.629 | 0.017 | 0.025 |
| D | 8.650 | 9.800 | 0.341 | 0.386 |
| d1 | 15.88 | 16.120 | 0.622 | 0.635 |
| d3 | 12.300 | 12.920 | 0.484 | 0.509 |
| E | 10.360 | 10.630 | 0.408 | 0.419 |
| e | 2.54 BSC | | 0.100 BSC | |
| L | 13.200 | 13.730 | 0.520 | 0.541 |
| L1 | 3.100 | 3.500 | 0.122 | 0.138 |
| n | 6.050 | 6.150 | 0.238 | 0.242 |
| Ø P | 3.050 | 3.450 | 0.120 | 0.136 |
| u | 2.400 | 2.500 | 0.094 | 0.098 |
| V | 0.400 | 0.500 | 0.016 | 0.020 |

ECN: E19-0180-Rev. D, 08-Apr-2019
DWG: 5972

Notes

1. To be used only for process drawing
2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
3. All critical dimensions should C meet $C_{pk} > 1.33$
4. All dimensions include burrs and plating thickness
5. No chipping or package damage
6. Facility code will be the 1st character located at the 2nd row of the unit marking



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